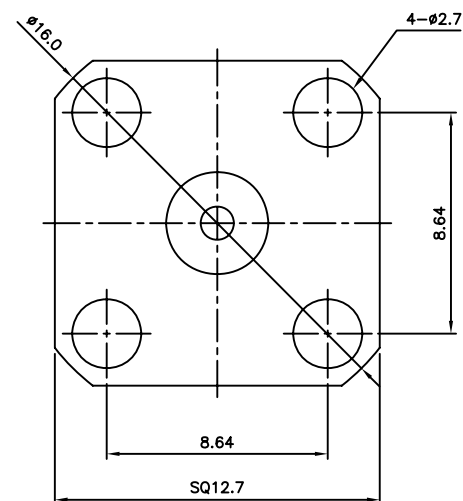
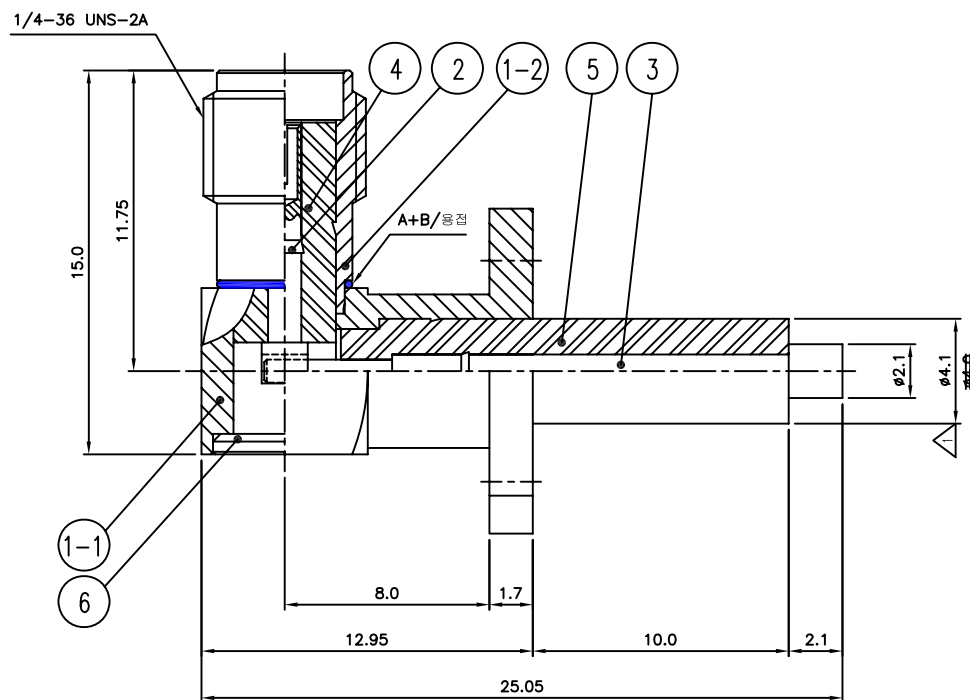


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
1	Initial Registration	I.C.KIM		2019.09.26.
2	[출판번호 202104-0003] 바디 PUNCH->HOCK 변경 및 A+B/월칭 구조 적용	S.Y.EUN	I.C.KIM	2021.04.09.
2	바디 골중량률 인한 코드 변경	S.Y.EUN	I.C.KIM	2021.07.06.



	6	COVER	1	MbsB C3604BD-F	Gold Plate	DCO00038-5/1
△	5	INSULATOR	1	TEFLON		DIN03087-N/2 DIN03087-N/2
	4	INSULATOR	1	TEFLON		DIN00112-N/1
	3	CONTACT	1	MbsB C3604BD-F	Gold Plate	DCT04065-5/1
	2	CONTACT	1	BcCu C17300	Gold Plate	DCT00151-5/1
△	1	i=2 BODY (B)		MbsB C3604BD-F	Gold Plate	DBD002134-1/3 DBD002134-1/3
△		i=1 BODY (A)	1	MbsB C3604BD-F	Gold Plate	DBD002134-1/3 DBD00229-1/5 DBD002134-1/3
		NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING CODE

TOLERANCE	Decimal	DATE		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017	
	±0.3	APPROVED BY	I.C.KIM		
	Angle	CHECKED BY	TITLE		
	±1°	DRAWN BY			
MATERIAL			SMA50 PCB JL-4R		
FINISH			SCALE	UNIT	 A3
			4/1	mm	
			DWG NO.		CN01342-7/5
			REVISION		2
			SHEET		1 of 1